



Recommended PCB Layout (Top View)



**Material and Finish**

Insulator: HT thermoplastic, UL94V-0 rated, black or white color, Reflow Process Compatible- Recommended Soldering Temperature: 230°C for 30 seconds, 260°C max.

Front Shield, Grounding Strip: brass, 0.30mm thick, 120u" nickel plated over 50u" copper underplate

Rear Shield: cold rolled steel, 0.30mm thick, 120u" nickel plated over 50u" copper underplate

Contact Material: phosphor bronze

Contact Plating Options:  
 Standard: gold flash on contact area, 120u" min. tin on soldertails, all over 50u" min. nickel underplate  
 -30 Option: 30u" gold on contact area, 120u" min. tin on soldertails, all over 50u" min. nickel underplate

Recommended PCB Thickness: 1.6mm

**Specifications:**

Contact Current Rating: 1A max.  
 Contact Resistance: 30 milliohms max.  
 Insulation Resistance: 1000 Megohms min.  
 Dielectric Withstanding Voltage: 750V AC  
 Insertion Force: 3.57kg max.  
 Extraction Force: 1.02kg min.  
 Operating Temperature: -25°C to +80°C  
 Durability: 1500 mating cycles min.

Part Number	Contact Area Plating	Insulator Color
KUSBLX-AS2N-W	Gold Flash (standard)	White
KUSBLX-AS2N-W30	30u" Gold (-30 option)	
KUSBLX-AS2N-B	Gold Flash (standard)	Black
KUSBLX-AS2N-B30	30u" Gold (-30 option)	

Tolerances
X.X ± 0.25
X.XX ± 0.15
Unless Stated Otherwise

REV.	DATE	DESCRIPTION	REV. BY	CHK. BY	DRAWN BY	DATE
A1	10/4/05	New Drawing	R. Aguirre	H. MA	R. Aguirre	8/01/05

**KUSBLX-AS2N-xxx**  
 xxx = color and plating options

Stacked A-Type USB Socket, RoHS Compliant  
 Low Profile Mount, PCB Mount, Right Angle

